

GTH0-0029220S **50V, DC – 2.9GHz, 220W GaN HEMT**

FEATURES

- Operating Frequency Range: DC to 2.9GHz
- Operating Drain Voltage: 28V & 50V
- Maximum Output Power (P_{SAT}): 220W
- Air Cavity Ceramic package
- Suitable for CW, Pulsed, Linear applications
- 100% DC & RF Production Tested



NI-360 Ceramic Package

DESCRIPTION

The GTH0-0029220S is a 220W (P3dB) unmatched discrete GaN-on-SiC HEMT which operates from DC to 2.9GHz on a 50V supply rail. The wide bandwidth of the GTH0-0029220S makes it suitable for a variety of applications including cellular infrastructure, radar, communications, and test instrumentation, and can support CW, linear and pulse operations.

The device is housed in an industry-standard NI-360 Air Cavity Ceramic package. Lead-free and RoHS compliant.

Typical Performances 1 Tone pulsed CW (10% duty cycle, 100µs width), 2nd Harmonics NOT optimized

- (1) Optimum Peak Power at 2.5dB in compression
- (2) Optimum Peak Efficiency at 2.5dB in compression

V_{ds}=50V, I_{dq}= 200 mA, T_A = 25°C

Frequency (MHz)	P _{out} ⁽¹⁾ (dBm)	Gain ⁽²⁾ (dB)	Eff ⁽²⁾ (%)
1500	53.5	22.3	72.8
2000	53.5	20.8	72
2500	53.4	18.2	67.1

V_{ds}=28V, I_{dq}= 200 mA, T_A = 25°C

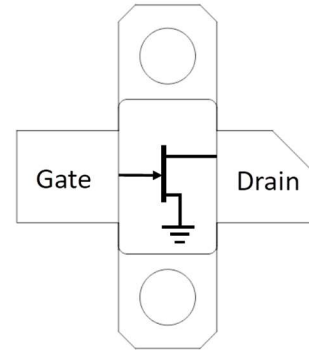
Frequency (MHz)	P _{out} ⁽¹⁾ (dBm)	Gain ⁽²⁾ (dB)	Eff ⁽²⁾ (%)
1500	51.2	20.1	72.9
2000	51	18.7	71.7
2500	50.8	16.1	68.5

ABSOLUTE MAXIMUM RATINGS^(1, 2)

Parameter	Rating	Symbols and Units
Drain Source Voltage	150	V_{DS} (V)
Gate Source Voltage	-8 to +2	V_{GS} (V)
Operating Voltage	55	V_{dsq} (V)
Junction Temperature	+225	T_{JUNC} (°C)
Storage Temperature	-65 to +150	$T_{STORAGE}$ (°C)
Case Operating Temperature	-40 to +105	T_{CASE} (°C)

1. Exceeding any of these limits may cause permanent damage to this device or seriously limit the life time (MTTF)
2. GalliumSemi does not recommend sustained operation above maximum operating conditions.

BLOCK DIAGRAM



ELECTRICAL SPECIFICATIONS: $T_A = 25^\circ\text{C}$

Parameter	Min.	Typ.	Max.	Symbols and Units	Test conditions
Frequency Range	DC		2900	MHz	
DC Characteristics					
Drain Source Breakdown Voltage	150			V_{BDSS} (V)	
Drain Source Leakage Current		9		I_{DLK} (mA)	$V_{gs} = -8V, V_{ds} = 50V$
Gate Threshold Voltage	-3.4		-1.5	V_{GS} (V)	$V_{ds} = 50V$
Operating Conditions					
Gate Bias Voltage		-2.5		V_{GSQ} (V)	
Drain Voltage		50		V_{DSQ} (V)	
Quiescent Drain Current		109		I_{DQ} (mA)	

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RF ELECTRICAL SPECIFICATIONS: $T_A = 25^\circ\text{C}$, $V_{DS} = 50\text{ V}$, $I_{DQ} = 200\text{ mA}$, $\text{Freq} = 2900\text{MHz}$
Note: Performance⁽¹⁾ in GalliumSemi Production Test Fixture, $50\ \Omega$ system

Parameter	Symbol	Min.	Typ.	Max.	Units	Notes
Small Signal Gain	G_{SS}		tbd		dB	
Power Gain	G_{SAT}		tbd		dB	
Saturated Drain Efficiency	$DEff_{SAT}$		tbd		%	
Saturated Output Power	P_{SAT}		tbd		dBm	
Ruggedness Output mismatch	Ψ	VSWR = 10:1, all angles				No damage or shift in performances

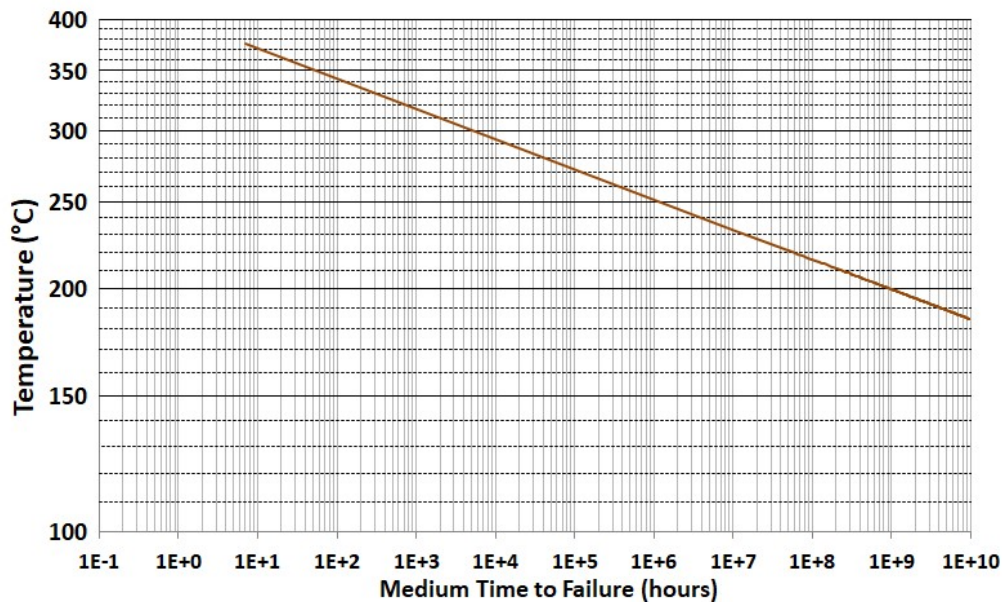
1. 1 Tone Pulse CW, pulse width 100us, duty cycle 10%

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THERMAL AND RELIABILITY INFORMATION -CW ^(1, 2, 3): T_c = 85°C

Parameter	Test condition	Value	Units	Notes
Channel Temperature, T _{ch}		151	°C	
R _{th}	P _{diss} 36 W	1.8	°C/W	
MTTF		> 1.0E10	Hrs	
Channel Temperature, T _{ch}		235	°C	
R _{th}	P _{diss} 75 W	2	°C/W	
MTTF		6.8E6	Hrs	
Channel Temperature, T _{ch}		321	°C	
R _{th}	P _{diss} 110 W	2.1	°C/W	
MTTF		170	Hrs	

- Using 5um thermal grease - 4W/m-K.
- Thermal Resistance using Finite Element Analysis (FEA) simulation, calibrated with Infrared measurement on surface temperature.
- R_{th} vs Dissipated Power can be generalized with the following equation: $R_{th}(^{\circ}C/W) = 0.0782x P_{diss(W)} + 1.6887$



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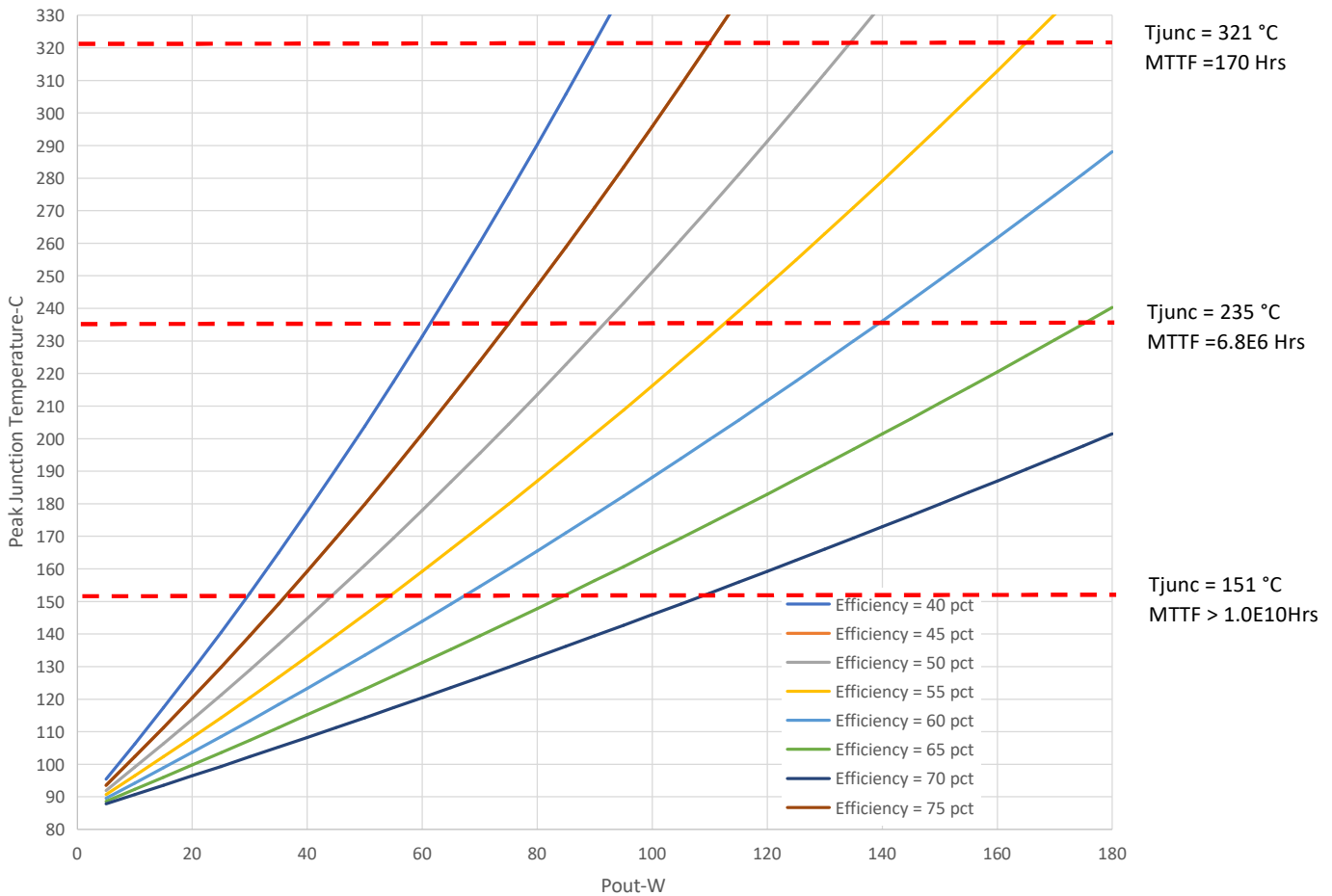
CW OPERATION

The device can withstand CW operation with respect to the application’s MTTF (Life time vs. Peak Junction Temperature).

The graph^(1,2) below shows the Peak Junction Temperature vs. the Output Power & Efficiency trade-off, using the following equations:

- $T_{junc}(^{\circ}C) = P_{diss(w)} \times R_{th}(^{\circ}C/W)$
 - $P_{diss(w)} = (P_{out(w)} / Efficiency(\%)) - P_{out(w)}$

E.g.: The device can be used for $P_{out} = 110\text{ W}$ CW with Efficiency of 55%, T_{junc} will be $235^{\circ}C$, leading to a LifeTime (MTTF) of $6.8E6\text{ Hrs}$.



Notes:

1. 5um thermal grease - 4W/m-K
2. Back of pkg is 85°C infinite heat sink

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LOADPULL MEASUREMENT, Vds= 50V Idq = 200 mA

1 Tone Pulse CW, pulse width 100us, duty cycle 10%

For Optimum Peak Power @ 2.5dB Compression

Freq-MHz	Zin_F0	Zl_F0	Gain-dB	Pout-dBm	Pout-W	Eff-%	AMPM-deg
1500	0.7 j -0.0	4.5 j -0.0	20.9	53.5	222.8	64.3	-1.3
2000	0.6 j 1.6	3.9 j -1.8	18.1	53.5	221.8	58.8	-0.8
2500	0.6 j 3.2	3.3 j -2.6	16.4	53.4	217.1	57.3	-1.1

For Optimum Peak Efficiency @ 2.5dB Compression

Freq-MHz	Zin_F0	Zl_F0	Gain-dB	Pout-dBm	Pout-W	Eff-%	AMPM-deg
1500	0.4 j 0.4	4.3 j 2.9	22.3	52.2	166.7	72.8	-3.9
2000	0.3 j 2.2	2.7 j 1.7	20.8	51.2	130.7	72	-5.6
2500	0.4 j 3.7	2.1 j -0.2	18.2	51.5	141.9	67.1	-6.9

LOADPULL MEASUREMENT, Vds= 28V Idq = 200 mA

1 Tone Pulse CW, pulse width 100us, duty cycle 10%

For Optimum Peak Power @ 2.5dB Compression

Freq-MHz	Zin_F0	Zl_F0	Gain-dB	Pout-dBm	Pout-W	Eff-%	AMPM-deg
1500	0.7 j -0.0	2.8 j -1.9	18	51.2	130.1	61.7	-1.5
2000	0.6 j 1.8	2.6 j -2.9	16.5	51	124	60.5	-1.5
2500	0.6 j 3.5	2.5 j -3.8	14.6	50.8	120.1	58.5	-2.3

For Optimum Peak Efficiency @ 2.5dB Compression

Freq-MHz	Zin_F0	Zl_F0	Gain-dB	Pout-dBm	Pout-W	Eff-%	AMPM-deg
1500	0.4 j 0.7	3.9 j 1.4	20.1	48.7	75.3	72.9	-3.5
2000	0.3 j 2.2	2.4 j -0.6	18.7	49.2	83.9	71.7	-5.9
2500	0.4 j 3.8	2.2 j -1.6	16.1	49	78.8	68.5	-6.2

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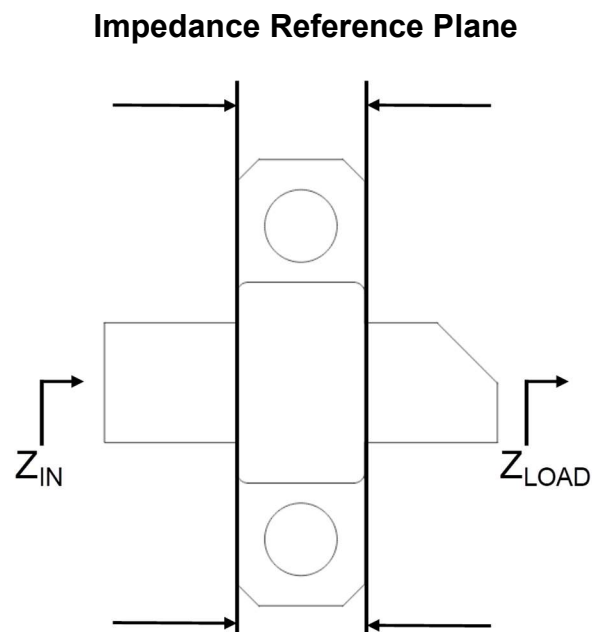
LOADPULL MEASUREMENT NOTES

Source and Load impedance @ 2nd Harmonic are set to 10 Ohms

With proper 2nd Harmonic termination, expect +5% Efficiency for Source and similar with Drain 2nd Harmonic.

Z_{LOAD} : Measured Impedance presented to the output of the device in the reference plane

Z_{IN} : Measured input Impedance at the input of the device in the reference plane

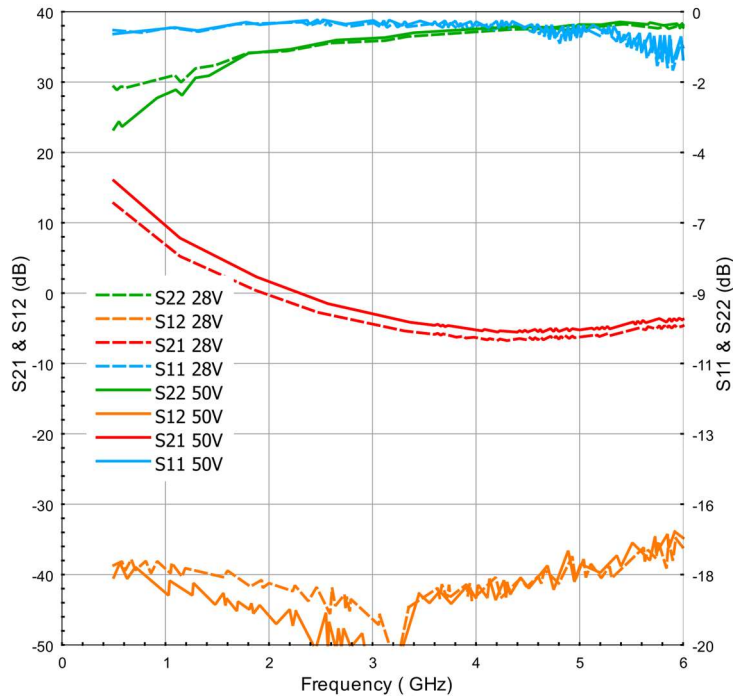


Raw data and full Loadpull measurement report available at request: sales@galliumsemi.com

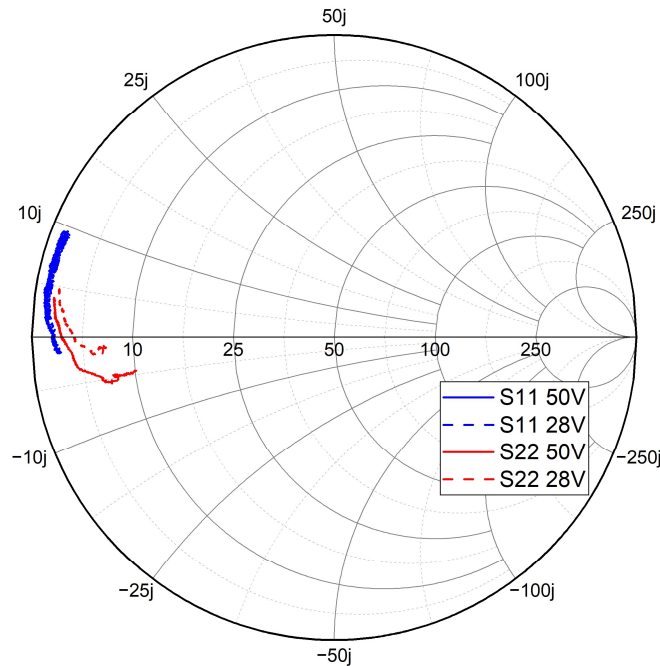
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BROADBAND S-PARAMETERS MEASUREMENT, $V_{ds}= 28 \text{ \& 50V}$ $I_{dq} = 200 \text{ mA}$
1 Tone CW

S Parameters (Mag-dB)



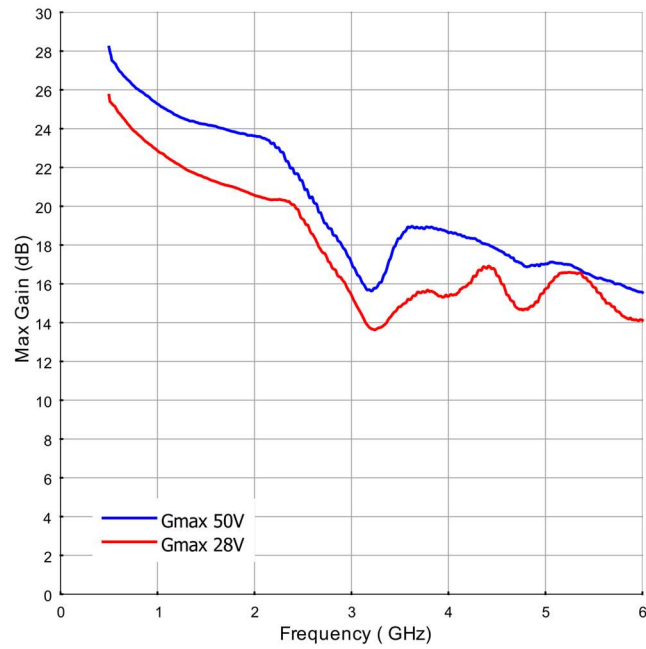
S11 & S22 0.7-8 GHz



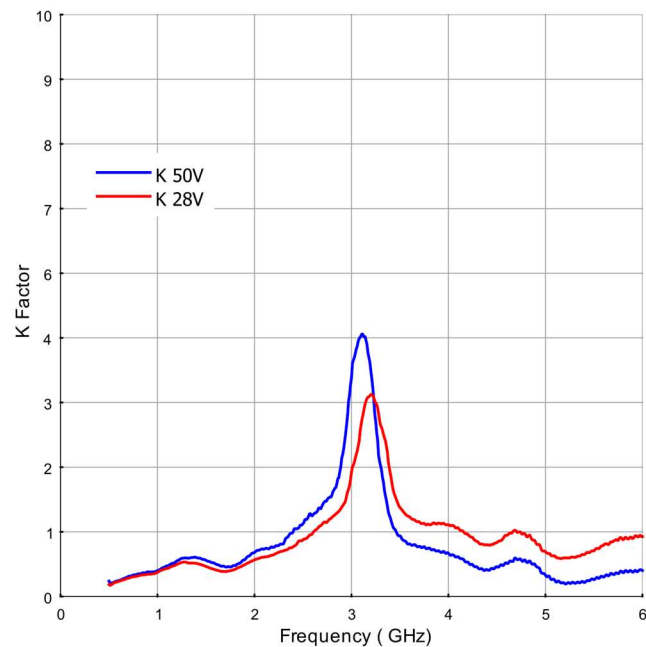
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BROADBAND S-PARAMETERS MEASUREMENT, $V_{ds} = 28$ & $50V$ $I_{dq} = 200$ mA
1 Tone CW

Maximum Available Gain



K Factor



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GaN HEMT BIASING SEQUENCE

To turn the transistor ON

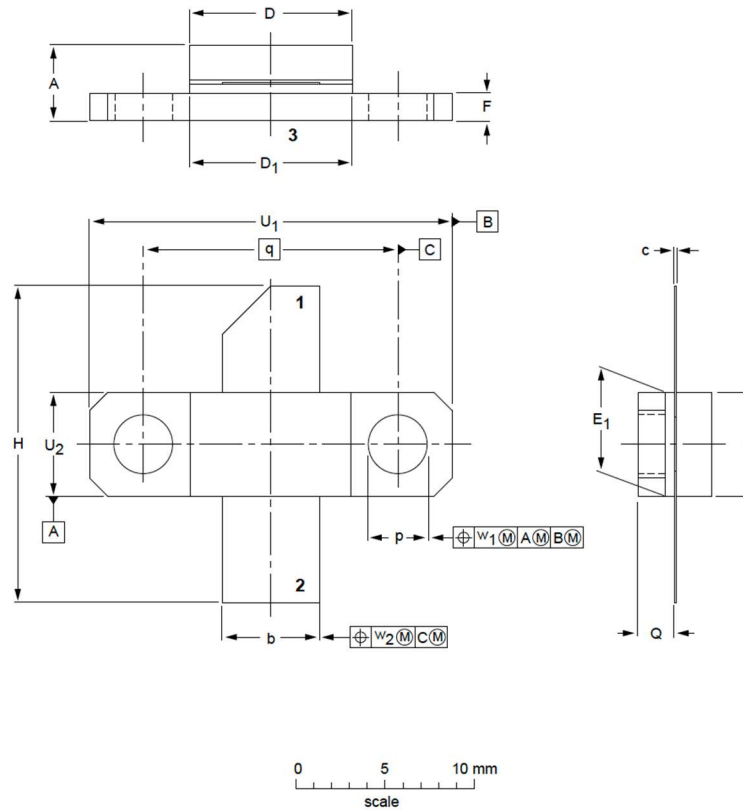
1. Set V_{GS} to -5V
2. Turn on V_{DS} to normal operation voltage (50V)
3. Slowly increase V_{GS} to set I_{DQ} current (200 mA)
4. Apply RF power

To turn the transistor OFF

1. Turn the RF power off
2. Decrease V_{GS} to -5V
3. Turn off V_D . Wait a few seconds for drain capacitor to discharge
4. Turn off V_{GS}

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PACKAGE DIMENSIONS



DIMENSIONS (millimetre dimensions are derived from the original inch dimensions)

UNIT	A	b	c	D	D ₁	E	E ₁	F	H	p	Q	q	U ₁	U ₂	w ₁	w ₂
mm	4.67 3.94	5.59 5.33	0.15 0.10	9.25 9.04	9.27 9.02	5.92 5.77	5.97 5.72	1.65 1.40	18.54 17.02	3.43 3.18	2.21 1.96	14.27	20.45 20.19	5.97 5.72	0.25	0.51
inch	0.184 0.155	0.220 0.210	0.006 0.004	0.364 0.356	0.365 0.355	0.233 0.227	0.235 0.225	0.065 0.055	0.73 0.67	0.135 0.125	0.087 0.077	0.562	0.805 0.795	0.235 0.225	0.010	0.020

PIN CONFIGURATION

Pin	Input/Output
1	RF Output / Drain Voltage
2	RF Input / Gate Voltage
3 (flange)	Ground

DEVICE LABEL

Line 1:	COMPANY NAME: GALLIUM
Line 2:	PART NUMBER - WAFER #
Line 3:	AA: Assembly Code
	YYWW: Assembly Date Code
	R: Reserved code

GTH0-0029220S**50V, DC – 2.9GHz, 220W GaN HEMT****HANDLING PRECAUTIONS**

Parameter	Symbol	Class	Test Methodology
ESD – Human Body Model	HBM	Class 1A (250 V)	ANSI/ESDA/JEDEC Standard JS-001
ESD – Charged Device Model	CDM	Class C3 (1500 V)	ANSI/ESDA/JEDEC Standard JS-002
MSL – Moisture Sensitivity Level	MSL	MSL 1	IPC/JEDEC Standard J-STD-020

**RoHS COMPLIANCE**

Gallium Semiconductor's Policy on EU RoHS available online:

https://www.galliumsemi.com/files/ugd/3748d3_1107b9788f9845f78f45d424097c4c97.pdf

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CONTACT INFORMATION

To request latest information and samples, please contact us at:

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Email: sales@galliumsemi.com

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